

# BNO086 Development Kit

Consisting of the BNO085 and BNO086, our BNO08X family of SiPs (System-in-Package) is perfect for robotics, AR/VR, HIDs (Human Interface Devices, such as remote controls) and other motion-sensing applications. Leveraging our advanced sensor fusion software and a Bosch Sensortec sensor, this powerful platform is highly flexible, and we'll work with your technology teams so you can easily configure it to bring out the best in your product.

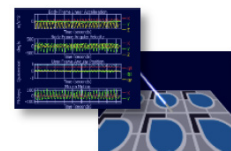
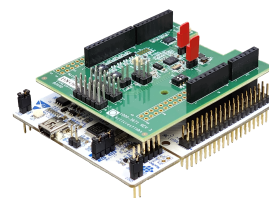
The BNO086 Development Kit is a demonstration and evaluation platform that allows quick and easy development and prototyping.



BNO086 Development Kit with STM32 Nucleo-F411RE

## WHAT'S INCLUDED

- ✔ **BNO086 Development Board** – Designed as a ‘shield’, it simply plugs into the STM32 Nucleo-F411RE prototyping platform
  - The board includes the BNO086 9-axis SiP, Bosch BME280 pressure/temperature/humidity, and Capella CM36686 proximity/ALS sensors
  - The board provides test points to measure the current consumption of the BNO086
  - Dimensions: 2.425" x 2.85"
- ✔ **ST Microelectronics STM32 Nucleo-F411RE Development Platform** – Pre-installed with the Communication Software Driver Package that fully implements the communication protocol used by the BNO086
- ✔ **Evaluation Toolset with Graphical Interface** - MotionStudio2.0 is a PC application that provides a graphical interface for evaluating sensor functionality, configuring devices, plotting and logging motion data, upgrading firmware, and developing products with motion technology
- ✔ **Technical Collateral and Documentation** - Includes all necessary source code, guides, reference manuals, datasheets and schematics for a quick and straight-forward installation



## ABOUT CEVA

CEVA is the leading licensor of wireless connectivity and smart sensing technologies. We offer Digital Signal Processors, AI processors, wireless platforms and complementary software for sensor fusion, image enhancement, computer vision, voice input and artificial intelligence, all of which are key enabling technologies for a smarter, more connected world. We partner with semiconductor companies and OEMs worldwide to create power-efficient, intelligent and connected devices for a range of end markets, including mobile, consumer, automotive, robotics, industrial and IoT. Our ultra-low-power IPs include comprehensive platforms comprised of specialized DSPs coupled with an AI and other types of accelerators targeted for low power workloads, including 5G baseband processing, intelligent vision, voice recognition, physical layer processing and sensor fusion. We also offer high performance DSPs targeted for 5G RAN and Open RAN, Wi-Fi enterprise and residential access points, satellite communication and other multi-gigabit communications. Our portfolio also includes a wide range of application software optimized for our processors, including voice front-end processing and speech recognition, imaging and computer vision and sensor fusion. For sensor fusion, our Hillcrest Labs sensor processing technologies provide a broad range of sensor fusion software and inertial measurement unit ("IMU") solutions for AR/VR, robotics, remote controls and IoT. For wireless IoT, we offer the industry's most widely adopted IPs for Bluetooth (low energy and dual mode), Wi-Fi 4/5/6 (802.11n/ac/ax) and NB-IoT.

